

REMARKS

I. STATUS OF THE CLAIMS

Claim 9 is canceled herein.

New claims 11-19 are added and are somewhat similar to claims 1-8 and 10, respectively.

In view of the above, it is respectfully submitted that claims 1-8 and 10-19 are currently pending.

II. OBJECTION TO THE TITLE

The Title is amended to overcome the objection.

III. REJECTION OF CLAIM 1-8 AND 10 UNDER 35 USC 103 AS BEING UNPATENTABLE OVER AOKI IN VIEW OF UEMURA

In the present invention as recited, for example, in claim 1, a substrate assembly for a gas discharge panel comprises a dielectric layer and a protective layer of MgO formed in this order on a substrate having electrodes.

As recited, for example, in claim 1, the dielectric layer is a laminate of an organic dielectric layer and an inorganic dielectric layer in this order from a side of the substrate.

With the configuration as recited, for example, in claim 1, the inorganic dielectric layer is between the protective layer and the organic dielectric layer. Please note that claim 1 is amended to clearly recite this feature.

With the inorganic dielectric layer between the protective layer and the organic dielectric layer, it is possible to prevent deterioration and peeling off of the organic dielectric layer. See, for example, page 20, lines 17-21, of the specification.

Aoki discloses a silicone resin having an alkyl group and an aryl group that is used for a dielectric layer. See, for example, paragraphs [0041], [0055] and [0062], of Aoki.

However, Aoki does not disclose or suggest that two dielectric layers are used. Therefore, Aoki does not disclose or suggest the use of an organic dielectric layer and an inorganic dielectric layer as recited, for example, in claim 1.

Uemura discloses a dielectric layer 26 made of a low melting point glass, a second metal oxide layer 27-1 made of TiO₂ and a first metal oxide layer 27-2 made of MgO. See, for example, column 5, lines 27-38; column 9, lines 1-4; and Example 3, of Uemura.

However, the first and second metal oxide layers of Uemura are a layer having a function as a protective layer. Moreover, Uemura does not describe that the second metal oxide layer

can be used as a dielectric layer. Therefore, it is respectfully submitted that Uemura lacks motivation to use two dielectric layers.

Further, as indicated above, with the inorganic dielectric layer between the protective layer and the organic dielectric layer as recited, for example, in claim 1, it is possible to prevent deterioration and peeling off of the organic dielectric layer. See, for example, page 20, lines 17-21, of the specification. In comparison, in Uemura, the second metal oxide layer is provided in order to match the linear thermal expansion coefficient of the protective layer to that of the dielectric layer, thereby preventing cracks in the protective layer.

Therefore, the reasons for providing the inorganic dielectric layer in embodiments of the present invention are completely different than the reasons for providing the second metal oxide layer in Uemura.

Accordingly, it is respectfully submitted that Aoki and Uemura should not be combined in the manner suggested by the Examiner and, even if combined, would not attain a structure as recited, for example, in claim 1.

In view of the above, it is respectfully submitted that the rejection is overcome.

IV. CONCLUSION

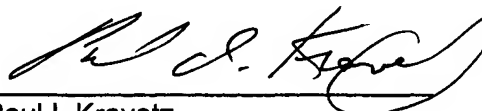
In view of the above, it is respectfully submitted that the application is in condition for allowance, and a Notice of Allowance is earnestly solicited.

If any further fees are required in connection with the filing of this response, please charge such fees to our Deposit Account No. 19-3935.

Respectfully submitted,

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